- Low-Voltage Differential Driver and Receiver for Half-Duplex Operation
- Designed for Signaling Rates of 400 Mbit/s
- ESD Protection Exceeds 15 kV on Bus Pins
- Operates From a Single 3.3-V Supply
- Low-Voltage Differential Signaling With Typical Output Voltages of 350 mV and a 50-Ω Load
- Valid Output With as Little as 50 mV Input Voltage Difference

Propagation Delay Times

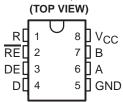
Driver: 1.7 ns TypReceiver: 3.7 ns Typ

Power Dissipation at 200 MHz

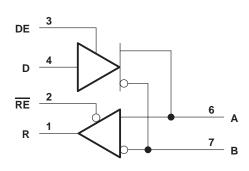
Driver: 50 mW TypicalReceiver: 60 mW Typical

- LVTTL Levels Are 5-V Tolerant
- Bus Pins Are High Impedance When Disabled or With V_{CC} Less Than 1.5 V
- Open-Circuit Fail-Safe Receiver
- Surface-Mount Packaging
 - D Package (SOIC)
 - DGK Package (MSOP)

SN65LVDM176D (Marked as DM176 or LVM176) SN65LVDM176DGK (Marked as M76)



logic diagram (positive logic)



description

The SN65LVDM176 is a differential line driver and receiver configured as a transceiver that uses low-voltage differential signaling (LVDS) to achieve signaling rates as high as 400 Mbit/s. These circuits are similar to TIA/EIA-644 standard compliant devices (SN65LVDS) counterparts except that the output current of the drivers is doubled. This modification provides a minimum differential output voltage magnitude of 247 mV into a $50-\Omega$ load and allows double-terminated lines and half-duplex operation. The receivers detect a voltage difference of less than 50 mV with up to 1 V of ground potential difference between a transmitter and receiver.

The intended application of this device and signaling technique is for half-duplex or multiplex baseband data transmission over controlled impedance media of approximately $100-\Omega$ characteristic impedance. The transmission media may be printed-circuit board traces, backplanes, or cables. (Note: The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other application specific characteristics).

The SN65LVDM176 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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AVAILABLE OPTIONS

	PACE	KAGE
TA	SMALL OUTLINE (D) [†]	MSOP (DGK) [†]
-40°C to 85°C	SN65LVDM176D	SN65LVDM176DGK

[†]The D package is available taped and reeled. Add the suffix R to the device type (e.g., SN65LVDM176DR).

Function Tables

DRIVER

INPUT	ENABLE	OUTI	PUTS
D	DE	Α	В
L	Н	L	Н
Н	Н	Н	L
Open	Н	L	Н
Х	L	Z	Z

H = high level, L = low level, X = irrelevant, Z = high impedance

RECEIVER

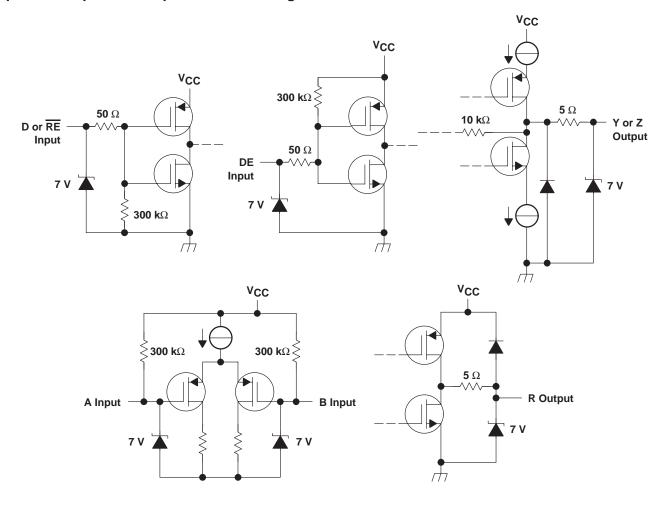
DIFFERENTIAL INPUTS $V_{ID} = V_A - V_B$	ENABLE RE	OUTPUT R
$V_{ID} \ge 50 \text{ mV}$	L	Н
$-50 \text{ mV} < \text{V}_{\text{ID}} < 50 \text{ mV}$	L	?
$V_{ID} \le -50 \text{ mV}$	L	L
Open	L	Н
X	Н	Z

H = high level, L = low level, X = irrelevant,

Z = high impedance



equivalent input and output schematic diagrams



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Input voltage range, D, R, DE, RE	–0.5 V to 6 V
A or B	0.5 V to 4 V
Electrostatic discharge; A, B, and GND (see Note 2)	CLass 3, A:15 kV, B:600 V
All terminals	Class 3, A:7 kV, B:500 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{Stq}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ Power rating	DERATING FACTOR ABOVE T _A = 25°C	T _A = 85°C POWER RATING	
D	725 mW	5.8 mW/°C	377 mW	
DGK	424 mW	3.4 mW/°C	220 mW	

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	3	3.3	3.6	V
High-level input voltage, VIH	2			V
Low-level input voltage, V _{IL}			0.8	V
Magnitude of differential input voltage, V _{ID}	0.1		0.6	V
Common-mode input voltage, V _{IC} (see Figure 1)	$\frac{\left V_{ID}\right }{2}$		$2.4 - \frac{ V_{ID} }{2}$	V
Operating free–air temperature, T _A	-40		V _{CC} -0.8	°C



NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

^{2.} Tested in accordance with MIL-STD-883C Method 3015.7.

COMMON-MODE INPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

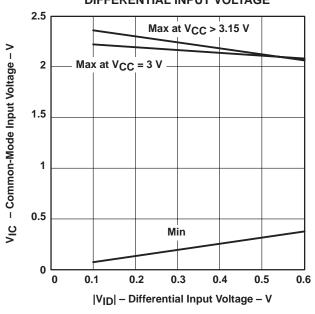


Figure 1

device electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
		Driver and receiver enabled, no receiver load, driver R _L = 50 Ω		10	15	
1	Driver enabled, receiver disabled, $R_L = 50 \Omega$		9	15		
ICC	Supply current	Driver disabled, receiver enabled, no load		1.8	5	mA
	Disabled		0.5	2		

[†] All typical values are at 25°C and with a 3.3-V supply.

SN65LVDM176 HIGH-SPEED DIFFERENTIAL LINE TRANSCEIVER

SLLS320D - DECEMBER 1998 - REVISED JULY 2000

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V _{OD}	Differential output voltage magnitude		D 500	247	340	454	
Δ V _{OD}	Change in differential output voltage magnitude betweestates	een logic	R_L = 50Ω, See Figure 2 and Figure 3	-50		50	mV
Voc(ss)	Steady-state common-mode output voltage			1.125		1.375	V
ΔVOC(SS)	Change in steady-state common-mode output voltage between logic states		See Figure 4	-50		50	mV
VOC(PP)	Peak-to-peak common-mode output voltage				50	150	mV
	High lavel input assessed	DE	V 5V		0.5	10	^
liH	High-level input current†	D	V _{IH} = 5 V		2	20	μΑ
	Law book Seed somet	DE	V 00V		-0.5	-10	•
ll∟	Low-level input current†	D	V _{IL} = 0.8 V		2	10	μΑ
			V_{OA} or $V_{OB} = 0$ V			-10	•
IOS Short-circuit output current-		$V_{OD} = 0 V$			-10	mA	
Cl	Input capacitance				3		pF

[†] The non-algebraic convention, where the more positive (least negative) limit is designated maximum, is used in this data sheet for this parameter.

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going differential input voltage threshold	Coo Figure C			50	\/
V _{IT} -	Negative-going differential input voltage threshold	See Figure 6	-50			mV
Vон	High-level output voltage	I _{OH} = -8 mA	2.4			V
VOL	Low-level output voltage	I _{OL} = 8 mA			0.4	V
	Leave to a man of the an D investable	V _I = 0 V	-2		-20	
"	Input current (A or B inputs)‡	V _I = 2.4 V	-1.2			μΑ
I _I (OFF)	Power-off input current (A or B inputs)	V _{CC} = 0 V or 1.8 V			20	μΑ
lіН	High-level input current (enables)	V _{IH} = 5 V			10	μΑ
I _I L	Low-level input current (enables)	V _{IL} = 0.8 V			10	μΑ
loz	High-impedance output current [‡]	$V_O = 0 \text{ V or } 5 \text{ V}$			±1	μΑ

[†] All typical values are at 25°C and with a 3.3-V supply.

[‡] The non-algebraic convention, where the more positive (least negative) limit is designated maximum, is used in this data sheet for this parameter.

SN65LVDM176 HIGH-SPEED DIFFERENTIAL LINE TRANSCEIVER

SLLS320D - DECEMBER 1998 - REVISED JULY 2000

driver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output		0.5	1.7	2.7	
tPHL	Propagation delay time, high-to-low-level output	$R_L = 50\Omega$,	0.5	1.7	2.7	ns
t _{sk(p)}	Pulse skew (tpHL - tpLH)	$C_{L} = 10 \text{ pF},$		0.2		ns
t _r	Differential output signal rise time	See Figure 3		0.6	1	
t _f	Differential output signal fall time			0.6	1	ns
t _{sk(pp)} ‡	Part-to-part skew				1	ns
^t PZH	Propagation delay time, high-impedance-to-high-level output			8	12	
tPZL	Propagation delay time, high-impedance-to-low-level output	0 5' 5		7	10	
^t PHZ	Propagation delay time, high-level-to-high-impedance output	See Figure 5		3	10	ns
^t PLZ	Propagation delay time, low-level-to-high-impedance output			4	10	

[†] All typical values are at 25°C and with a 3.3 V supply.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output		2.3	3.7	4.5	
tPHL	Propagation delay time, high-to-low-level output		2.3	3.7	4.5	ns
tsk(p)	Pulse skew (t _{pHL} - t _{pLH})	C _L = 10 pF, See Figure 7		0.4		
t _r	Output signal rise time	Coc rigulo r		0.8	1.5	
t _f	Output signal fall time			0.8	1.5	ns
t _{sk(pp)} ‡	Part-to-part skew				1	ns
^t PZH	Propagation delay time, high-level-to-high-impedance output			3	10	
tPZL	Propagation delay time, low-level-to-low-impedance output	0		3	10	
^t PHZ	Propagation delay time, high-impedance-to-high-level output	See Figure 8		4	10	ns
^t PLZ	Propagation delay time, low-impedance-to-high-level output			6	10	

[†] All typical values are at 25°C and with a 3.3-V supply.

[‡]t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

[‡]t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

driver

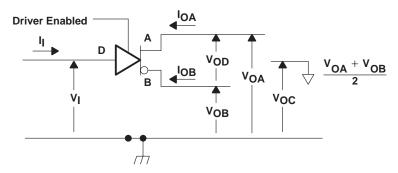
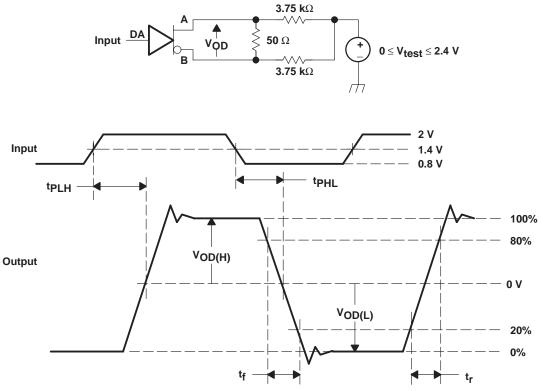


Figure 2. Driver Voltage and Current Definitions

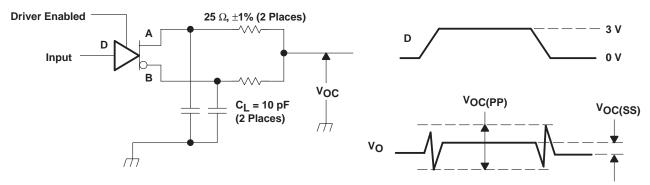


NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns . C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 3. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal

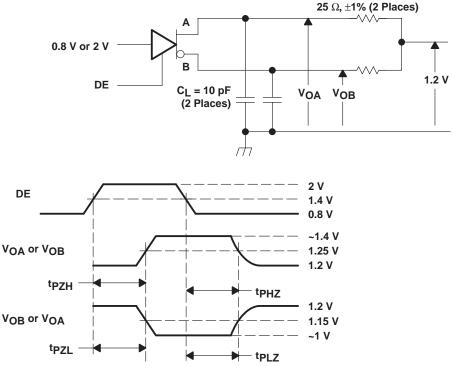


driver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or t_f ≤ 1 ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns . C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T. The measurement of V_{OC}(PP) is made on test equipment with a −3 dB bandwidth of at least 300 MHz.

Figure 4. Test Circuit and Definitions for the Driver Common-Mode Output Voltage



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_{Γ} or $t_{\Gamma} \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns . C_{L} includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 5. Enable and Disable Time Circuit and Definitions

receiver

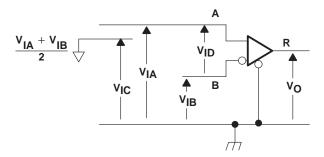
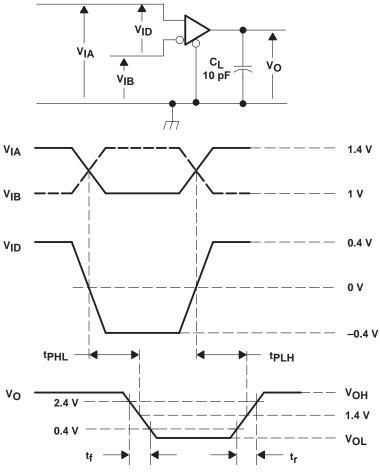


Figure 6. Receiver Voltage Definitions

Table 1. Receiver Minimum and Maximum Input Threshold Test Voltages

	VOLTAGES V)	RESULTING DIFFERENTIAL INPUT VOLTAGE (mV)	RESULTING COMMON- MODE INPUT VOLTAGE (V)
VIA	V _{IB}	V _{ID}	VIC
1.225	1.175	50	1.2
1.175	1.225	-50	1.2
2.41	2.36	50	2.385
2.36	2.41	-50	2.385
0.05	0	50	0.025
0	0.05	-50	0.025
1.5	0.9	600	1.2
0.9	1.5	-600	1.2
2.4	1.8	600	2.1
1.8	2.4	-600	2.1
0.6	0	600	0.3
0	0.6	-600	0.3

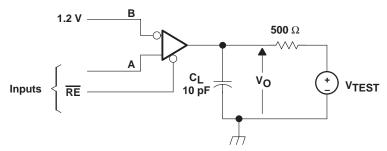
receiver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 7. Timing Test Circuit and Waveforms

receiver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_{Γ} or $t_{\bar{f}} \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 5000 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

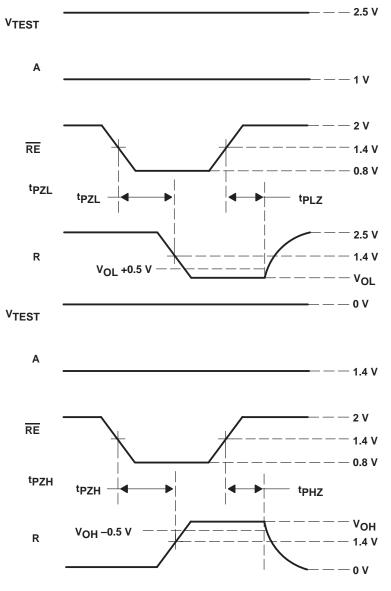
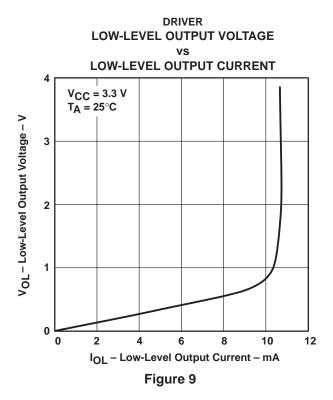
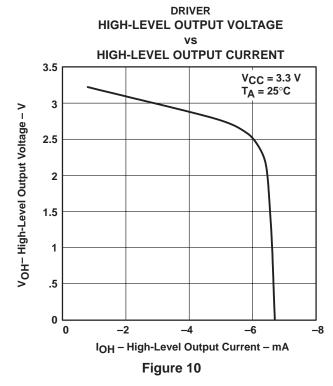


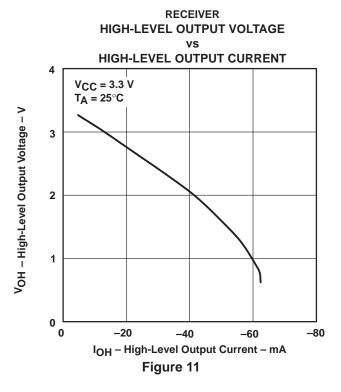
Figure 8. Enable/Disable Time Test Circuit and Waveforms

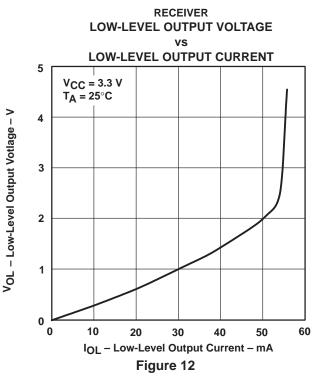


TYPICAL CHARACTERISTICS









TYPICAL CHARACTERISTICS

DRIVER HIGH-TO-LOW LEVEL PROPAGATION DELAY TIME

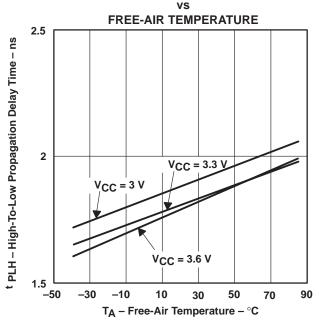


Figure 13

DRIVER LOW-TO-HIGH LEVEL PROPAGATION DELAY TIME

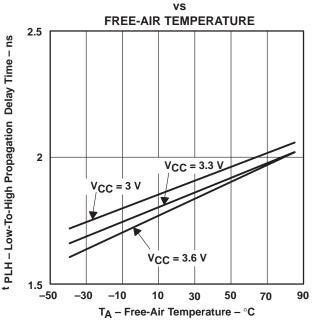


Figure 14

RECEIVER HIGH-TO-LOW LEVEL PROPAGATION DELAY TIME

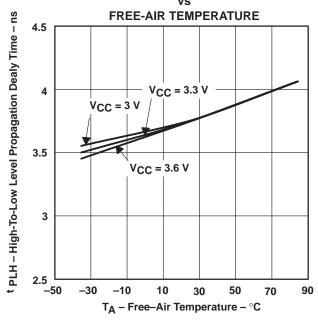


Figure 15

RECEIVER LOW-TO-HIGH LEVEL PROPAGATION DELAY TIME

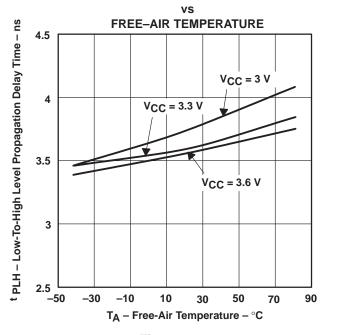


Figure 16

APPLICATION INFORMATION

The devices are generally used as building blocks for high-speed point-to-point data transmission. Ground differences are less than 1 V with a low common-mode output and balanced interface for very low noise emissions. Devices can interoperate with RS-422, PECL, and IEEE-P1596. Drivers/receivers maintain ECL speeds without the power and dual supply requirements.

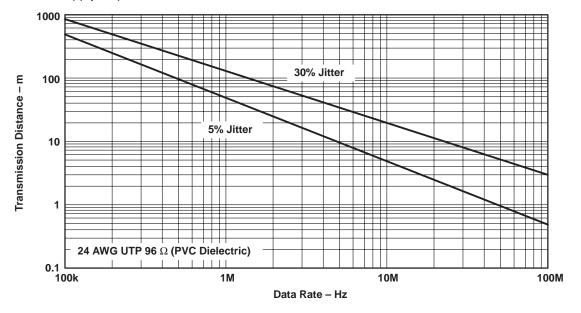


Figure 17. Data Transmission Distance Versus Rate

APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –50 mV and 50 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different in how it handles the open-input circuit situation, however.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near V_{CC} through 300-k Ω resistors as shown in Figure 18. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.

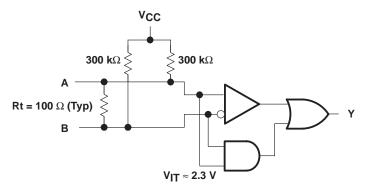
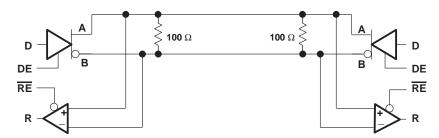


Figure 18. Open-Circuit Fail Safe of the LVDS Receiver

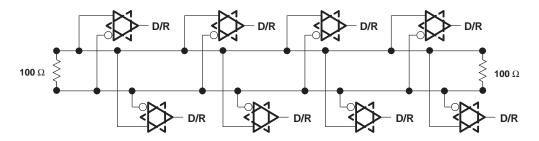
It is only under these conditions that the output of the receiver will be valid with less than a 50-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.



APPLICATIONS INFORMATION



Bidirectional Half-Duplex Applications



Multipoint Bus Applications

Note A: Keep drivers and receivers as close to the LVDS bus side connector as possible.

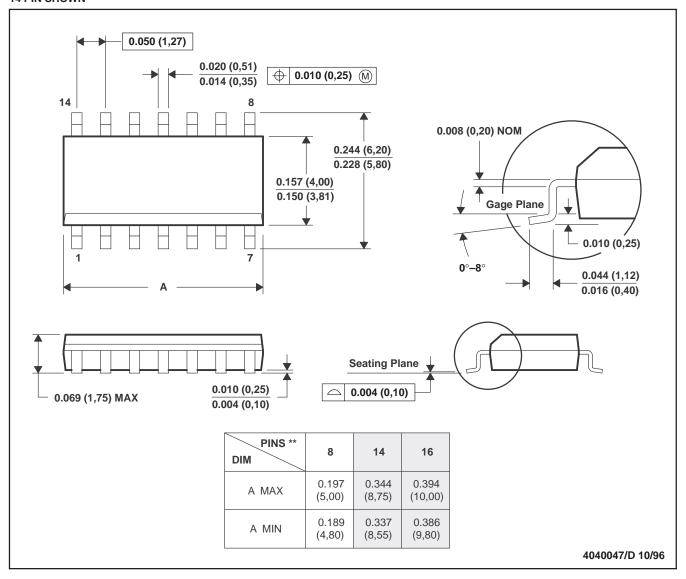
Figure 19. Bidirectional Half-Duplex and Multipoint Bus Applications

MECHANICAL DATA

D (R-PDSO-G**)

14 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

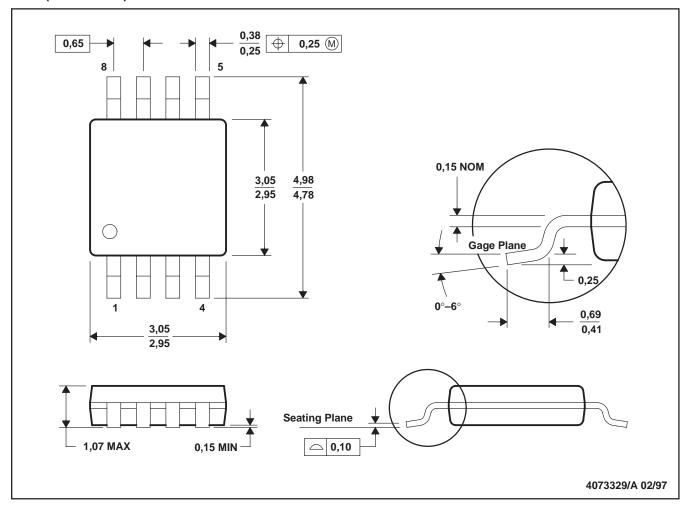
D. Falls within JEDEC MS-012



MECHANICAL DATA

DGK (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-187

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